



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260922003.2	PCN Issued	September 23, 2026
Qualify 0.8mil Cu wire diameter for select devices		Sample request deadline:	November 22, 2026
		Estimated 1st ship date:	March 22, 2027
Sample requests received after November 22, 2026 will not be supported.			

Change Type(s)	Assembly Material
ZVEI ID	SEM-PA-08

PCN Details

Description of Change:										
Texas Instruments Incorporated is announcing the qualification of 0.8mil Cu wire diameter for select devices listed in the "Product Affected" Section.										
Wire Diameter:										
	Current	Proposed								
Wire Diameter	1.0mil Cu wire	0.8mil Cu wire								
Qual details are provided in the Qual Data Section.										
Reason for Change:	Continuity of supply. Long term reliability improvement by reducing bond pad stress through optimized wire diameter									
Anticipated impact on Form, Fit, Function, Quality or Reliability:	Request the Supporting Data Packet (SDP) for more details on the changes.									
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table><tr><td>RoHS</td><td>REACH</td><td>Green Status</td><td>IEC 62474</td></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>		RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change
RoHS	REACH	Green Status	IEC 62474							
☒ No Change	☒ No Change	☒ No Change	☒ No Change							
Changes to product identification resulting from this PCN:	None									

Products Affected:	
TPS70930QDBVRM3Q 1	TPS70933QDBVRM3Q 1

Automotive Qualification Summary (As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 06-August -2026

Product Attributes

Attributes	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	QBS Package Reference: TLV1185QDBVRQ1	QBS Process Reference: TPS65248QDBVRQ1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Package Reference: PMB74LVCA017DBVRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management	Power Management	Signal Chain	Power Management	Power Management	Power Management	Logic
Wafer Fab Supplier	RFA8	MH8	RFA8	MH8	RFA8	RFA8	RFA8	MH8	RFA8
Assembly Site	PHI	PHI	PHI	PHI	PHI	CLARK,AT	PHI	PHI	PHI
Package Group	SOT	SOT	SOT	SOT	QFN	SOT	SOT	SOT	SOT
Package Designator	DBV	DBV	DBV	DBV	DBV	RHA	DBV	DBV	DBV
Pin Count	5	5	5	5	6	40	5	5	6

QBS: Qual By Similarity, also known as Generic Data

Qual Device TPS70930QDBVRM3Q1 is qualified at MSL1 260C

Qual Device TPS70930QDBVRM3Q1 is qualified at MSL1 260C

Qual Device TPS70933QDBVRM3Q1 is qualified at MSL1 260C

Qual Device TPS70933QDBVRM3Q1 is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Mfg Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	QBS Package Reference: TLV1185QDBVRQ1	QBS Process Reference: TPS65248QDBVRQ1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Package Reference: PMB74LVCA017DBVRQ1
Test Group A - Accelerated Environment Stress Tests																
PC	A1	JEDEC J-STD-020 JESD22-A118	3	77	Preconditioning	MSL1 260C	-	1/100	1/100 ¹	-	-	3/100	-	-	-	1/100
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/770	-	-	-	3/2310	-	-	-	1/770
ACU/HAST	A3	JEDEC JESD22-A100/JEDEC JESD22-A118	3	77	Autoclave	121C/15psq	96 Hours	-	-	-	-	3/2310	-	-	-	-
ACU/HAST	A3	JEDEC JESD22-A100/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	1/770	-	-	-	-	-	-	-	1/770
TC	A4	JEDEC JESD22-A104 and Appendix B	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/770	1/770	-	-	-	-	-	-	1/770
TC-SP	A4	MIL-STD-883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/50	1/50	-	-	1/50	-	-	-	1/50
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	1/450	-	-	-	-	-	-	-	1/450
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	-	3/1350	-	-	-	-
Test Group B - Accelerated Lifetime Simulation Tests																
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	-	-	3/2310	1/770	1/870	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	3/24000	-	-	-
Test Group C - Package Assembly Integrity Tests																
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpn>1.67	Wires	1/300	1/300	-	-	3/900	-	-	-	1/300
WBP	C2	MIL-STD-883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpn>1.67	Wires	1/300	1/300	-	-	3/900	-	-	-	1/300
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	-	1/150	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	-	1/150	-	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpn>1.67	-	1/100	1/100	-	-	3/900	-	-	-	1/100
Test Group D - Die Fabrication Reliability Tests																
EM	D1	JESD41	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD36	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD40 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests																
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/30	1/30	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	-	-	-	-	1/30	1/30	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	Corner pins	750 Volts	-	-	-	-	-	-	-	-	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	-	-	-	-	-	1/30	1/30	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpn>1.67 Room, hot and cold	-	-	-	-	-	-	-	3/900	3/900	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2604-104

[1]-Bandgap trim algorithm used the legacy methodology which is not fully optimized. Refer to 8D report for more details.

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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